

Customer No.: 31561  
Application No.: 10/709,923  
Docket NO.: 10788-US-PA

**REMARKS**

In response to the Restriction Requirement mailed on August 11, 2005, a complete listing of all of the claims is presented herewith. Applicant would like to elect Group II, claims 6-14, drawn to a process for a flip chip package, classified in class 438, subclass 15+. Please cancel Group I, claims 1-5, drawn to a flip chip package substrate, classified in class 257, subclass 778 without waiver, prejudice or disclaimer:

If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Date: *Sept. 9, 2005*

Respectfully submitted,

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